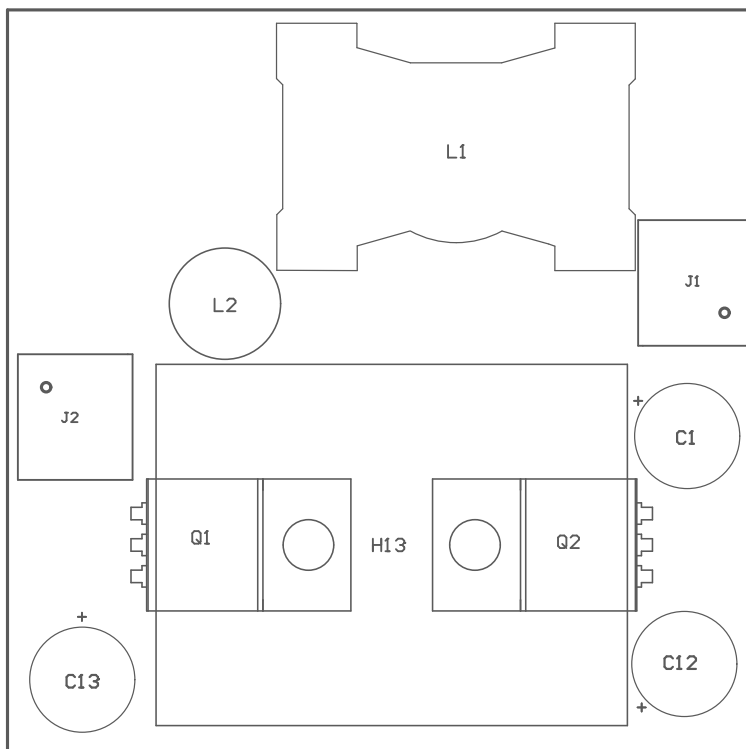


Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

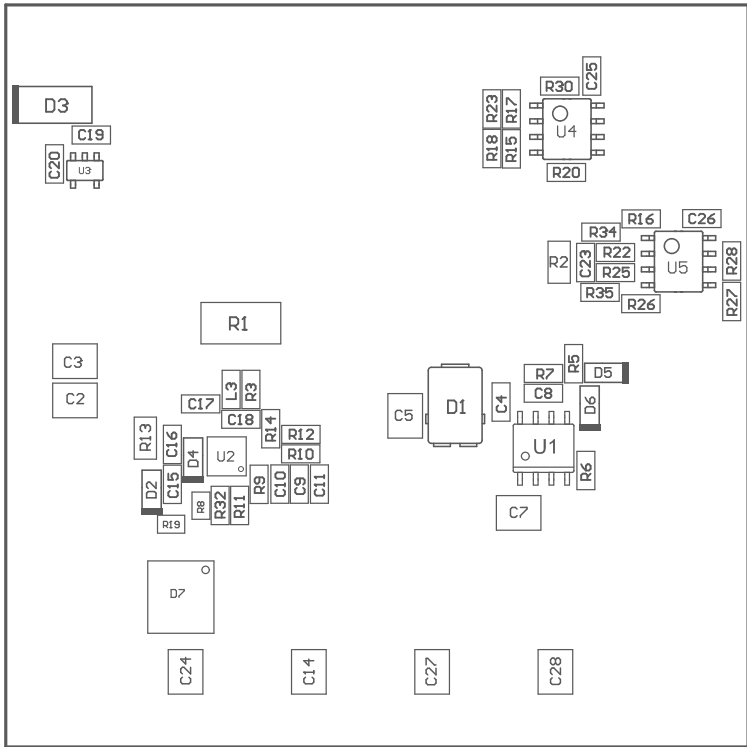
Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01558	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M5 Assembly Top	TID #: TIDA-01558		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/12/2017 12:10:39 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01558	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M6 Assembly Bottom	TID #: TIDA-01558		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/12/2017 12:10:40 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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